Dual General Purpose Transistor

The MBT3906DW1 device is a spin-off of our popular SOT-23/SOT-323 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-363 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

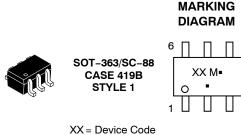
Features

- h_{FE}, 100–300
- Low $V_{CE(sat)}$, $\leq 0.4 V$
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Available in 8 mm, 7–inch/3,000 Unit Tape and Reel
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant*



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M = Date Code

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	-40	Vdc
Collector – Base Voltage	V _{CBO}	-40	Vdc
Emitter – Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous	Ι _C	-200	mAdc
Electrostatic Discharge	ESD	HBM Class 2 MM Class B	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Package Dissipation (Note 1) T _A = 25°C	P _D	150	mW
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	833	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

 Device mounted on FR4 glass epoxy printed circuit board using the minimum recommended footprint.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Semiconductor Components Industries, LLC, 2013 August, 2019 – Rev. 7

⁼ Pb-Free Package

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

	Characteristic	Symbol	Min	Мах	Unit
OFF CHARACTE	RISTICS				
Collector – Emitter	Breakdown Voltage (Note 2)	V _{(BR)CEO}	-40	-	Vdc
Collector - Base Br	eakdown Voltage	V _{(BR)CBO}	-40	-	Vdc
Emitter – Base Brea	akdown Voltage	V _{(BR)EBO}	-5.0	-	Vdc
Base Cutoff Currer	nt	I _{BL}	_	-50	nAdc
Collector Cutoff Cu	irrent	I _{CEX}	_	-50	nAdc
ON CHARACTER	RISTICS (Note 2)				•
(I _C = −1.0 mAdc, (I _C = −10 mAdc, (I _C = −50 mAdc,	$V_{CE} = -1.0 \text{ Vdc})$ $V_{CE} = -1.0 \text{ Vdc})$ $V_{CE} = -1.0 \text{ Vdc})$ $V_{CE} = -1.0 \text{ Vdc})$ $V_{CE} = -1.0 \text{ Vdc})$	h _{FE}	60 80 100 60 30	_ 300 _	_
$\label{eq:local_constraint} \begin{split} & \text{Collector}-\text{Emitter} \\ & (\text{I}_{\text{C}}=-10 \text{ mAdc}, \\ & (\text{I}_{\text{C}}=-50 \text{ mAdc}, \end{split}$	$I_B = -1.0 \text{ mAdc})$	V _{CE(sat)}	-	-0.25 -0.4	Vdc
$\begin{array}{l} \text{Base}-\text{Emitter Satu}\\ (\text{I}_{\text{C}}=-10 \text{ mAdc},\\ (\text{I}_{\text{C}}=-50 \text{ mAdc}, \end{array}$	$I_B = -1.0 \text{ mAdc}$)	V _{BE(sat)}	-0.65 -	-0.85 -0.95	Vdc
SMALL-SIGNAL	CHARACTERISTICS				
Current-Gain - Ba	andwidth Product	fT	250	-	MHz
Output Capacitanc	e	C _{obo}	-	4.5	pF
Input Capacitance		C _{ibo}	_	10.0	pF
Input Impedance (V _{CE} = -10 Vdc,	I _C = -1.0 mAdc, f = 1.0 kHz)	h _{ie}	2.0	12	kΩ
Voltage Feedback (V _{CE} = -10 Vdc,	Ratio I _C = −1.0 mAdc, f = 1.0 kHz)	h _{re}	0.1	10	X 10 ⁻⁴
Small – Signal Current Gain (V _{CE} = -10 Vdc, I _C = -1.0 mAdc, f = 1.0 kHz)		h _{fe}	100	400	-
Output Admittance (V _{CE} = -10 Vdc,	I _C = -1.0 mAdc, f = 1.0 kHz)	h _{oe}	3.0	60	μmhos
Noise Figure (V _{CE} = -5.0 Vdc, I _C = -100 μ Adc, R _S = 1.0 k Ω , f = 1.0 kHz)		NF	-	4.0	dB
SWITCHING CH	ARACTERISTICS	• • •		*	÷
Delay Time	(V _{CC} = -3.0 Vdc, V _{BE} = 0.5 Vdc)	t _d	-	35	
Rise Time	(I _C = -10 mAdc, I _{B1} = -1.0 mAdc)	t _r	-	35	ns
	1			1	-

2. Pulse Test: Pulse Width \leq 300 µs; Duty Cycle \leq 2.0%.

Storage Time

Fall Time

 $(V_{CC} = -3.0 \text{ Vdc}, I_C = -10 \text{ mAdc})$

 $(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$

ts

t_f

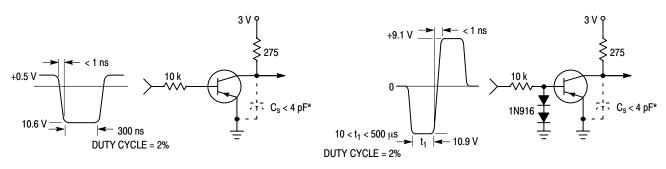
225

75

ns

_

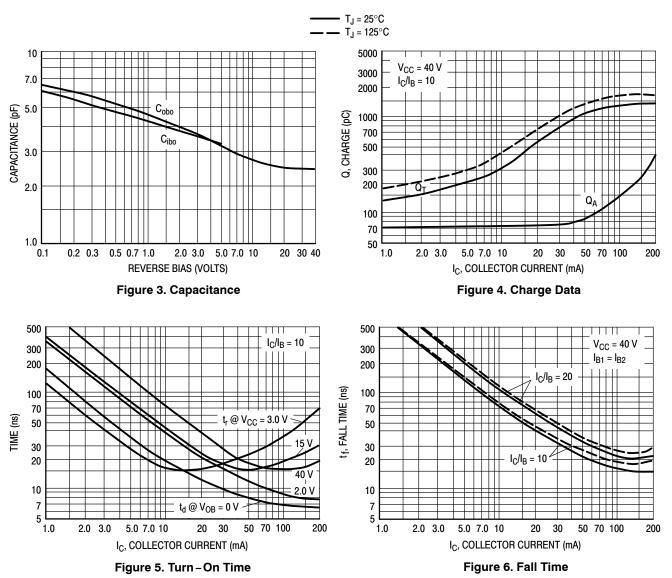
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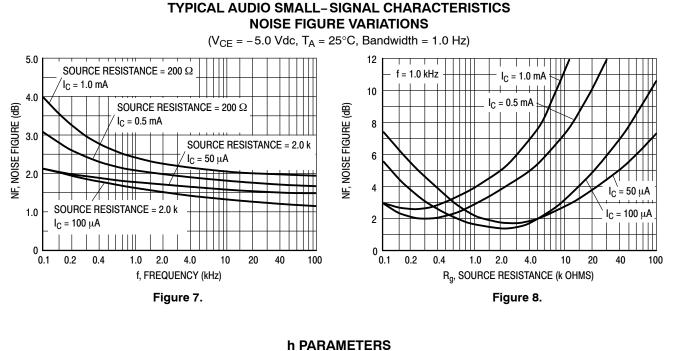
* Total shunt capacitance of test jig and connectors

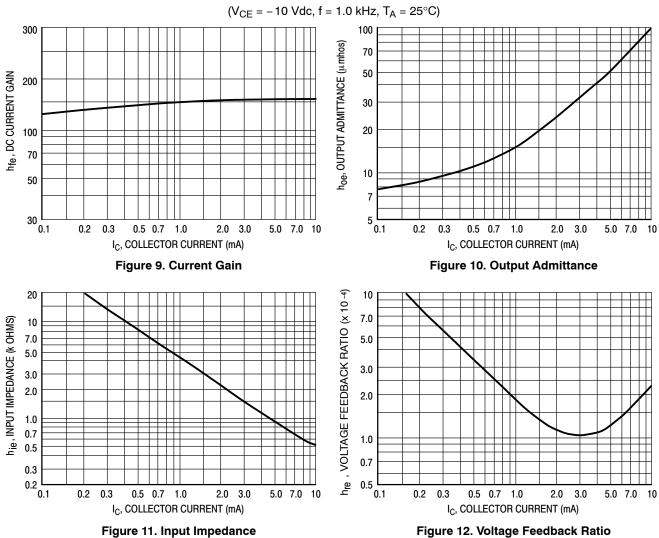
Figure 1. Delay and Rise Time Equivalent Test Circuit

Figure 2. Storage and Fall Time Equivalent Test Circuit



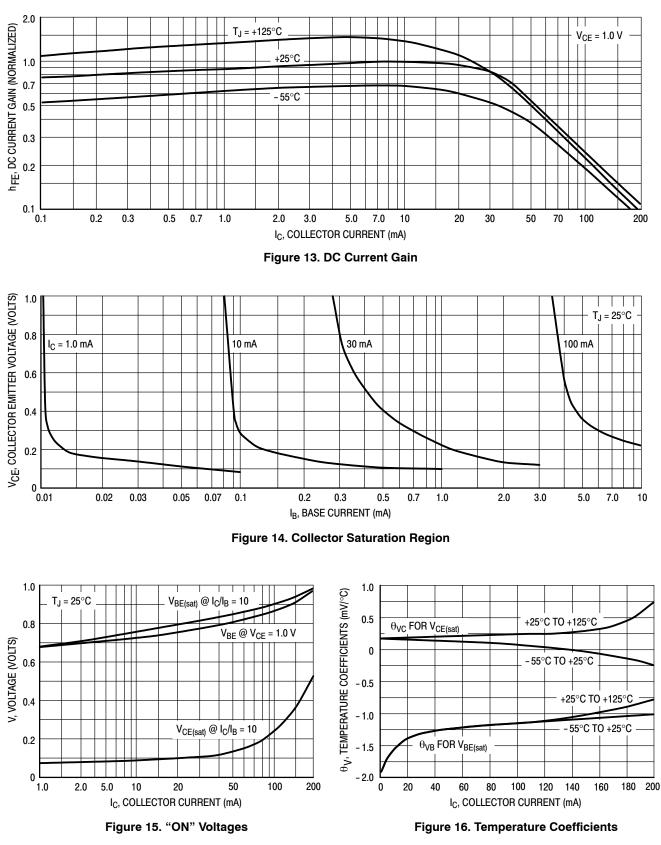
TYPICAL TRANSIENT CHARACTERISTICS





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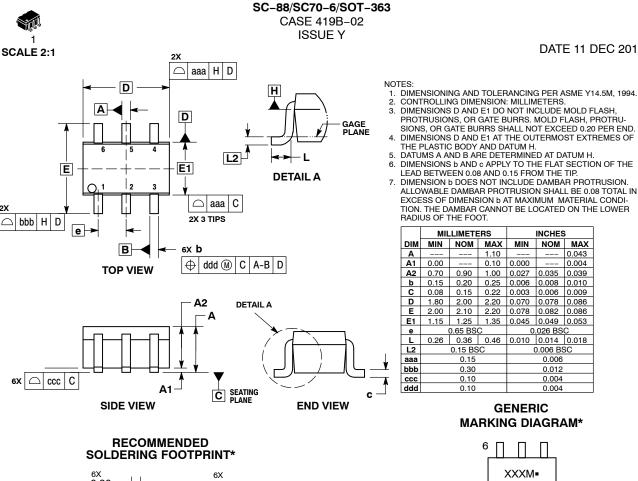
DEVICE ORDERING INFORMATION

Device	Marking	Pin Out	Package	Shipping [†]
MBT3906DW1T1G	A2		SOT-363 (Pb-Free)	3000 / Tape & Reel
SMBT3906DW1T1G	A2		SOT-363 (Pb-Free)	3000 / Tape & Reel
SMBT3906DW3T1G	A3		SOT-363 (Pb-Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DOSEM

DATE 11 DEC 2012



6X 0.30 -0.66 2 50 0.65 PITCH DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- CONTROLLING DIMENSION: MILLIMETERS. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRU-SIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H. DATUMS A AND B ARE DETERMINED AT DATUM H. DIMENSIONS b AND ¢ APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP. DIMENSION b DOCE NOT INCLUDE DAMAGE PROTEINSION

- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDI-TION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			1.10			0.043
A1	0.00		0.10	0.000		0.004
A2	0.70	0.90	1.00	0.027	0.035	0.039
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.070	0.078	0.086
Е	2.00	2.10	2.20	0.078	0.082	0.086
E1	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65 BSC		0.026 BSC			
L	0.26	0.36	0.46	0.010	0.014	0.018
L2	0.15 BSC			(0.006 BS	SC
aaa	0.15			0.006		
bbb	0.30			0.012		
ccc	0.10			0.004		
ddd	0.10				0.004	

GENERIC **MARKING DIAGRAM***



XXX = Specific Device Code

- = Date Code* М
- = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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DATE 11 DEC 2012

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13:	STYLE 14:	STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:
PIN 1. ANODE	PIN 1. VREF	PIN 1. ANODE 1	PIN 1. BASE 1	PIN 1. BASE 1	PIN 1. VIN1
2. N/C	2. GND	2. ANODE 2	2. EMITTER 2	2. EMITTER 1	2. VCC
3. COLLECTOR	3. GND	3. ANODE 3	3. COLLECTOR 2	3. COLLECTOR 2	3. VOUT2
4. EMITTER	4. IOUT	4. CATHODE 3	4. BASE 2	4. BASE 2	4. VIN2
5. BASE	5. VEN	5. CATHODE 2	5. EMITTER 1	5. EMITTER 2	5. GND
6. CATHODE	6. VCC	6. CATHODE 1	6. COLLECTOR 1	6. COLLECTOR 1	6. VOUT1
STYLE 19:	STYLE 20:	STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:
PIN 1. I OUT	PIN 1. COLLECTOR	PIN 1. ANODE 1	PIN 1. D1 (i)	PIN 1. Vn	PIN 1. CATHODE
2. GND	2. COLLECTOR	2. N/C	2. GND	2. CH1	2. ANODE
3. GND	3. BASE	3. ANODE 2	3. D2 (i)	3. Vp	3. CATHODE
4. V CC	4. EMITTER	4. CATHODE 2	4. D2 (c)	4. N/C	4. CATHODE
5. V EN	5. COLLECTOR	5. N/C	5. VBUS	5. CH2	5. CATHODE
6. V REF	6. COLLECTOR	6. CATHODE 1	6. D1 (c)	6. N/C	6. CATHODE
STYLE 25:	STYLE 26:	STYLE 27:	STYLE 28:	STYLE 29:	STYLE 30:
PIN 1. BASE 1	PIN 1. SOURCE 1	PIN 1. BASE 2	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. SOURCE 1
2. CATHODE	2. GATE 1	2. BASE 1	2. DRAIN	2. ANODE	2. DRAIN 2
3. COLLECTOR 2	3. DRAIN 2	3. COLLECTOR 1	3. GATE	3. COLLECTOR	3. DRAIN 2
4. BASE 2	4. SOURCE 2	4. EMITTER 1	4. SOURCE	4. EMITTER	4. SOURCE 2
5. EMITTER	5. GATE 2	5. EMITTER 2	5. DRAIN	5. BASE/ANODE	5. GATE 1
6. COLLECTOR 1	6. DRAIN 1	6. COLLECTOR 2	6. DRAIN	6. CATHODE	6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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